

TSSOP-28

Surface Mount Device
Lead

Short Product Overview

May 2010

Chip Card & Security

TSOPP-28 Short Product Overview	Ref.: Chip_Card_Product_Overview_11/09
Revision History: Current Version 05.10	
Previous Releases:	
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Important: Further information is confidential and on request. Please contact:
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Product name	TSSOP-28
Picture	
Product description	Surface Mount Device Lead
Typical Applications	Embedded Security Trusted Platform Module
Pitch	0.65 mm
Dimensions	Body: 9.7 x 4.4 mm
Thickness	max. 1.1mm
Contact Surface	Sn
Delivery form	Tape on Reel Reel diameter 330mm
ISO - reference	-
Derivatives	-

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